

TL07x Low-Noise JFET-Input Operational Amplifiers

1 Features

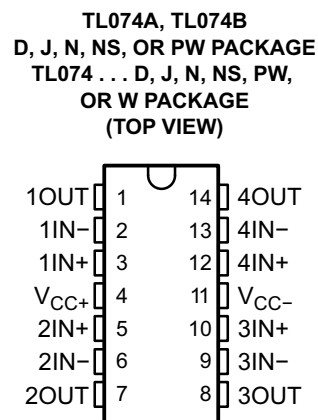
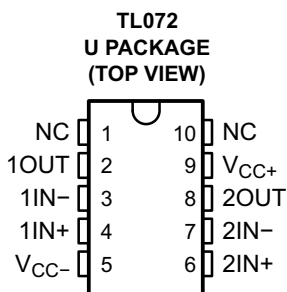
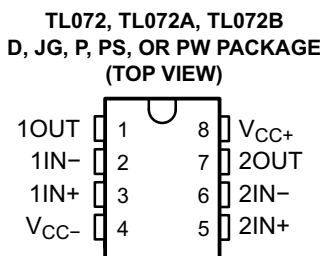
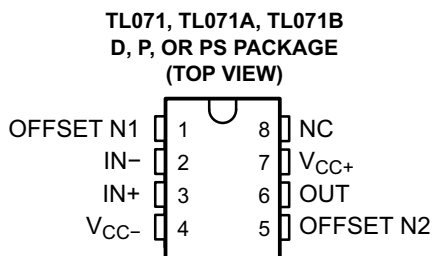
- Low Power Consumption
- Wide Common-Mode and Differential Voltage Ranges
- Low Input Bias and Offset Currents
- Output Short-Circuit Protection
- Low Total Harmonic Distortion: 0.003% Typ
- Low Noise
 $V_n = 18 \text{ nV}/\sqrt{\text{Hz}}$ Typ at $f = 1 \text{ kHz}$
- High Input Impedance: JFET Input Stage
- Internal Frequency Compensation
- Latch-Up-Free Operation
- High Slew Rate: $13 \text{ V}/\mu\text{s}$ Typ
- Common-Mode Input Voltage Range
Includes V_{CC+}

2 Description

The JFET-input operational amplifiers in the TL07x series are similar to the TL08x series, with low input bias and offset currents and fast slew rate. The low harmonic distortion and low noise make the TL07x series ideally suited for high-fidelity and audio preamplifier applications. Each amplifier features JFET inputs (for high input impedance) coupled with bipolar output stages integrated on a single monolithic chip.

The C-suffix devices are characterized for operation from 0°C to 70°C . The I-suffix devices are characterized for operation from -40°C to 85°C . The M-suffix devices are characterized for operation over the full military temperature range of -55°C to 125°C .

3 Terminal Out Drawings



NC – No internal connection



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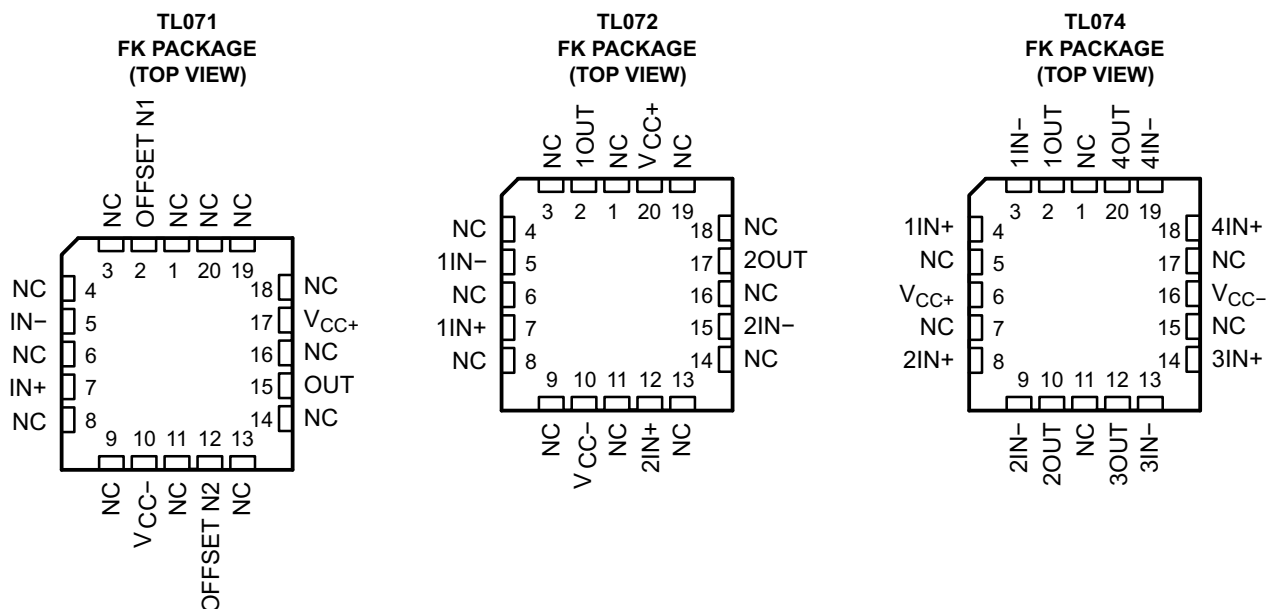
4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision J (March 2005) to Revision K	Page
• Updated document to new TI datasheet format - no specification changes.	1
• Added ESD warning.	17

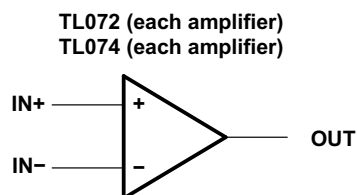
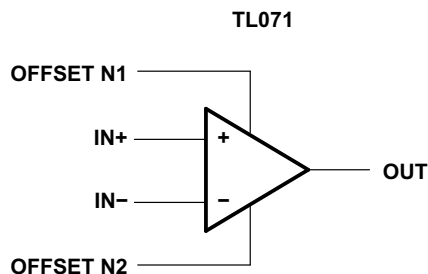
Changes from Revision K (January 2014) to Revision L	Page
• Moved T_{stg} to Handling Ratings table.	5
• Added missing Electrical Characteristics table.	6
• Added Device and Documentation Support section.	17
• Added Mechanical, Packaging, and Orderable Information section.	17

5 Terminal Configuration and Functions

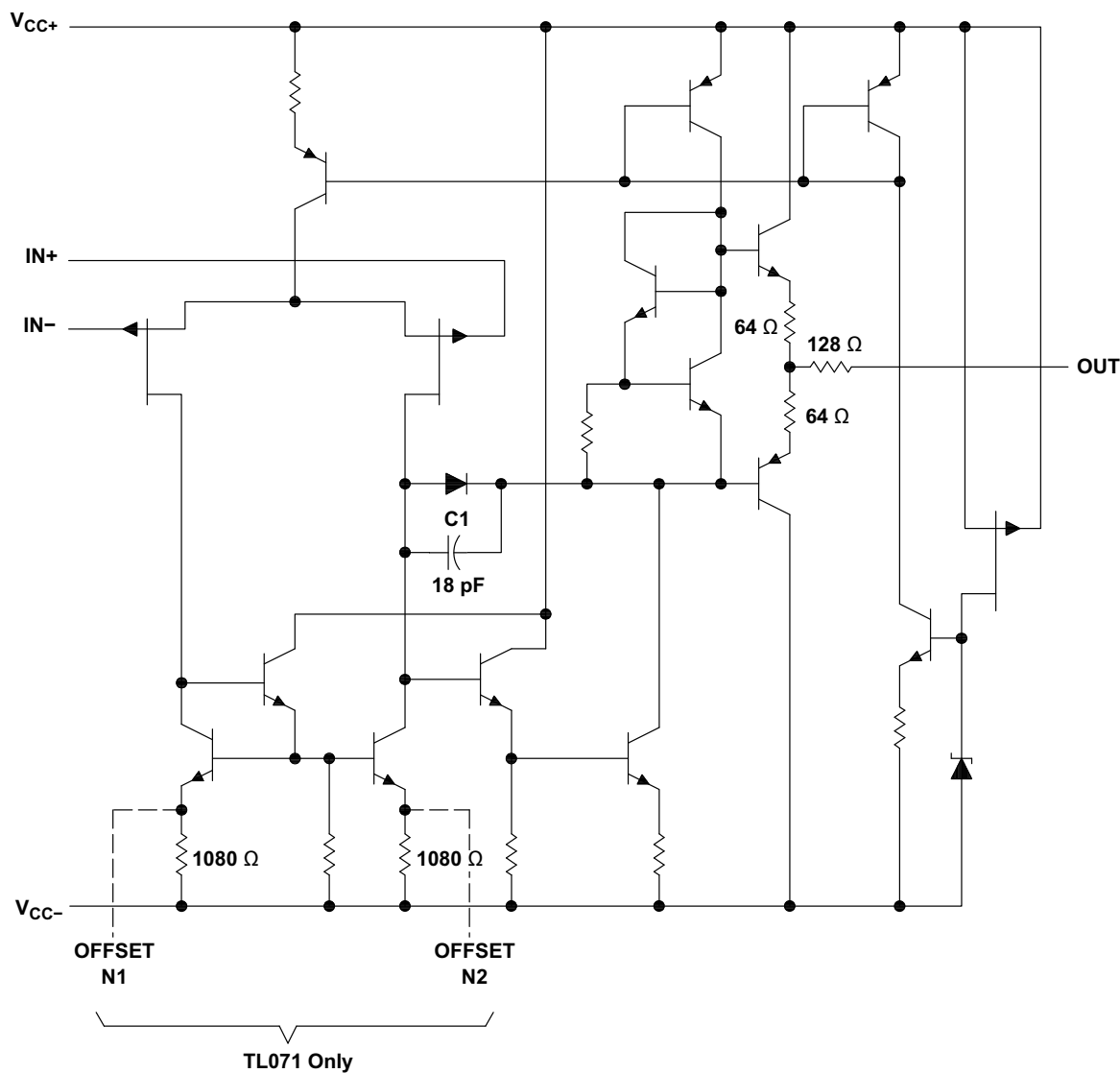


NC – No internal connection

Symbols



Schematic (Each Amplifier)



All component values shown are nominal.

COMPONENT COUNT†			
COMPONENT TYPE	TL071	TL072	TL074
Resistors	11	22	44
Transistors	14	28	56
JFET	2	4	6
Diodes	1	2	4
Capacitors	1	2	4
epi-FET	1	2	4

† Includes bias and trim circuitry

6 Specifications

6.1 Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			VALUE	UNIT
V _{CC+}	Supply voltage ⁽²⁾		18	V
V _{CC−}			−18	
V _{ID}	Differential input voltage ⁽³⁾		±30	V
V _I	Input voltage ⁽²⁾⁽⁴⁾		±15	V
Duration of output short circuit ⁽⁵⁾			Unlimited	
θ _{JA}	Package thermal impedance ⁽⁶⁾⁽⁷⁾	D package (8 pin)	97	°C/W
		D package (14 pin)	86	
		N package	80	
		NS package	76	
		P package	85	
		PS package	95	
		PW package (8 pin)	149	
		PW package (14 pin)	113	
θ _{JC}	Package thermal impedance ⁽⁸⁾⁽⁹⁾	U package	185	°C/W
		FK package	5.61	
		J package	15.05	
		JG package	14.5	
T _J	Operating virtual junction temperature		150	°C
	Case temperature for 60 seconds	FK package	260	°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds		J, JG, or W package	300	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-}.
- (3) Differential voltages are at IN+, with respect to IN–.
- (4) The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
- (5) The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
- (6) Maximum power dissipation is a function of T_{J(max)}, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_{J(max)} – T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can affect reliability.
- (7) The package thermal impedance is calculated in accordance with JESD 51-7.
- (8) Maximum power dissipation is a function of T_{J(max)}, θ_{JC}, and T_C. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_{J(max)} – T_C)/θ_{JC}. Operating at the absolute maximum T_J of 150°C can affect reliability.
- (9) The package thermal impedance is calculated in accordance with MIL-STD-883.

6.2 Handling Ratings

PARAMETER	DEFINITION	VALUE	UNIT
T _{stg}	Storage temperature range	–65 to 150	°C

6.3 Electrical Characteristics

$V_{CC} \pm \pm 15\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS ⁽¹⁾	T_A ⁽²⁾	TL071C TL072C TL074C			TL071AC TL072AC TL074AC			TL071BC TL072BC TL074BC			TL071I TL072I TL074I			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO} Input offset voltage	$V_O = 0$, $R_S = 50\ \Omega$	25°C		3	10		3	6		2	3		3	6	mV
		Full range			13			7.5			5			8	
$^aV_{IO}$ Temperature coefficient of input offset voltage	$V_O = 0$, $R_S = 50\ \Omega$	Full range		18			18			18			18		$\mu\text{V}/^\circ\text{C}$
I_{IO} Input offset current	$V_O = 0$	25°C		5	100		5	100		5	100		5	100	pA
		Full range			10			2			2			2	nA
I_{IB} Input bias current ⁽³⁾	$V_O = 0$	25°C		65	200		65	200		65	200		65	200	pA
		Full range			7			7			7			7	nA
V_{ICR} Common-mode input voltage range		25°C	± 11	–12 to 15		± 11	–12 to 15		± 11	–12 to 15		± 11	–12 to 15		V
V_{OM} Maximum peak output voltage swing	$R_L = 10\ \text{k}\Omega$	25°C	± 12	± 13.5		± 12	± 13.5		± 12	± 13.5		± 12	± 13.5		V
	$R_L \geq 10\ \text{k}\Omega$	Full range	± 12			± 12			± 12			± 12			
	$R_L \geq 2\ \text{k}\Omega$		± 10			± 10			± 10			± 10			
A_{VD} Large-signal differential voltage amplification	$V_O = \pm 10\text{ V}$, $R_L \geq 2\ \text{k}\Omega$	25°C	25	200		50	200		50	200		50	200		V/mV
		Full range	15			25			25			25			
B_1 Unity-gain bandwidth		25°C		3			3			3			3		MHz
r_i Input resistance		25°C		10^{12}			10^{12}			10^{12}			10^{12}		Ω
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICRmin}$, $V_O = 0$, $R_S = 50\ \Omega$	25°C	70	100		75	100		75	100		75	100		dB
k_{SVR} Supply-voltage rejection ratio ($\Delta V_{CC}/\Delta V_{IO}$)	$V_{CC} = \pm 9\text{ V to } \pm 15\text{ V}$, $V_O = 0$, $R_S = 50\ \Omega$	25°C	70	100		80	100		80	100		80	100		dB
I_{CC} Supply current (each amplifier)	$V_O = 0$, No load	25°C		1.4	2.5		1.4	2.5		1.4	2.5		1.4	2.5	mA
V_{OI}/V_O Crosstalk attenuation	$A_{VD} = 100$	25°C		120			120			120			120		dB

- (1) All characteristics are measured under open-loop conditions with zero common-mode voltage, unless otherwise specified.
- (2) Full range is $T_A = 0^\circ\text{C}$ to 70°C for TL07_C, TL07_AC, TL07_BC and is $T_A = -40^\circ\text{C}$ to 85°C for TL07_I.
- (3) Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 4. Pulse techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.

6.4 Electrical Characteristics

 $V_{CC\pm} = \pm 15\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS ⁽¹⁾	T _A ⁽²⁾	TL071M TL072M			TL074M			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V _{IO}	Input offset voltage	V _O = 0, R _S = 50 Ω	25°C		3	6		3	9	mV
			Full range			9			15	
α _{VIO}	Temperature coefficient of input offset voltage	V _O = 0, R _S = 50 Ω	Full range		18			18		μV/°C
I _{IO}	Input offset current	V _O = 0	25°C		5	100		5	100	pA
			Full range			20			20	nA
I _{IB}	Input bias current	V _O = 0	25°C		65	200		65	200	pA
						50			20	nA
V _{ICR}	Common-mode input voltage range		25°C	±11	–12 to 15		±11	–12 to 15		V
V _{OM}	Maximum peak output voltage swing	R _L = 10 kΩ	25°C	±12	±13.5		±12	±13.5		V
		R _L ≥ 10 kΩ	Full range	±12			±12			
		R _L ≥ 2 kΩ		±10			±10			
A _{VD}	Large-signal differential voltage amplification	V _O = ±10 V, R _L ≥ 2 kΩ	25°C	35	200		35	200		V/mV
				15			15			
B ₁	Unity-gain bandwidth				3			3		MHz
r _i	Input resistance				10 ¹²			10 ¹²		Ω
CMRR	Common-mode rejection ratio	V _{IC} = V _{ICRmin} , V _O = 0, R _S = 50 Ω	25°C	80	86		80	86		dB
k _{SVR}	Supply-voltage rejection ratio (ΔV _{CC±} /ΔV _{IO})	V _{CC} = ±9 V to ±15 V, V _O = 0, R _S = 50 Ω	25°C	80	86		80	86		dB
I _{CC}	Supply current (each amplifier)	V _O = 0, No load	25°C		1.4	2.5		1.4	2.5	mA
V _{O1} /V _{O2}	Crosstalk attenuation	A _{VD} = 100	25°C		120			120		dB

- (1) Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 4. Pulse techniques must be used that will maintain the junction temperature as close to the ambient temperature as possible.
- (2) All characteristics are measured under open-loop conditions with zero common-mode voltage, unless otherwise specified. Full range is $T_A = -55^\circ\text{C}$ to 125°C .

6.5 Operating Characteristics

 $V_{CC\pm} = \pm 15\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TL07xM			ALL OTHERS			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
SR Slew rate at unity gain	$V_I = 10\text{ V}$, $C_L = 100\text{ pF}$, $R_L = 2\text{ k}\Omega$, See Figure 1	5	13		8	13		V/ μs
t_r Rise-time overshoot factor	$V_I = 20\text{ V}$, $C_L = 100\text{ pF}$, $R_L = 2\text{ k}\Omega$, See Figure 1		0.1			0.1		μs
			20			20		%
V_n Equivalent input noise voltage	$R_S = 20\ \Omega$	$f = 1\text{ kHz}$			18			$\text{nV}/\sqrt{\text{Hz}}$
		$f = 10\text{ Hz}$ to 10 kHz			4			μV
I_n Equivalent input noise current	$R_S = 20\ \Omega$, $f = 1\text{ kHz}$		0.01			0.01		$\text{pA}/\sqrt{\text{Hz}}$
THD Total harmonic distortion	$V_{I rms} = 6\text{ V}$, $R_L \geq 2\text{ k}\Omega$, $f = 1\text{ kHz}$, $A_{VD} = 1$, $R_S \leq 1\text{ k}\Omega$		0.003			0.003		%

7 Parameter Measurement Information

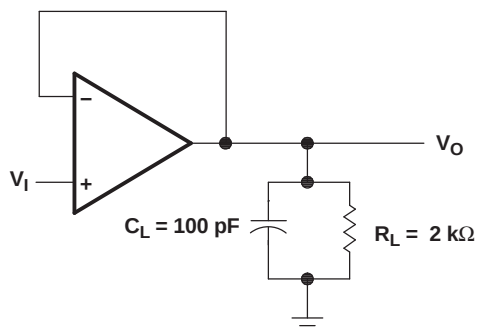


Figure 1. Unity-Gain Amplifier

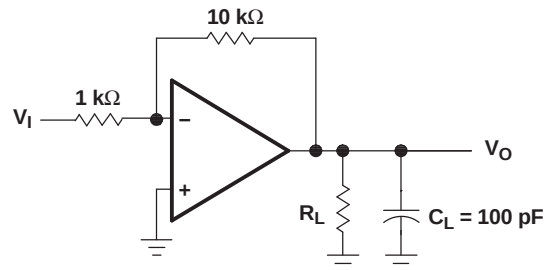


Figure 2. Gain-of-10 Inverting Amplifier

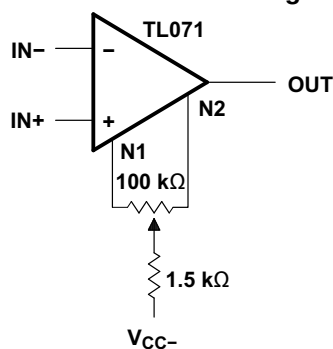


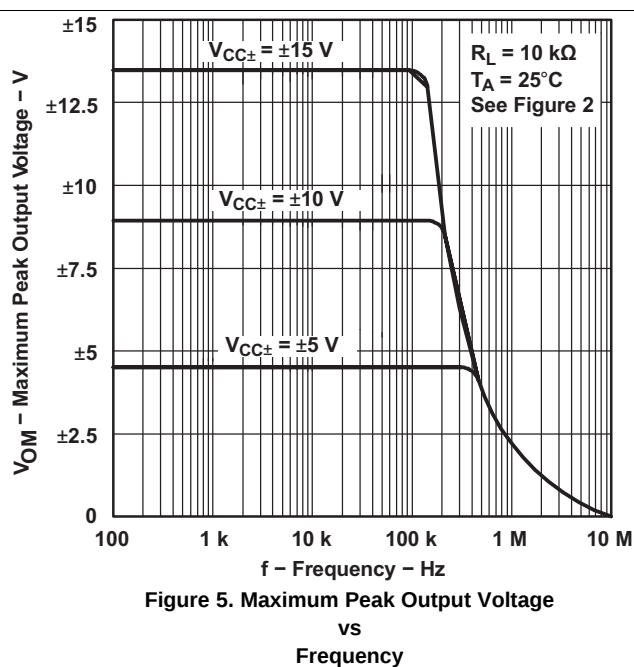
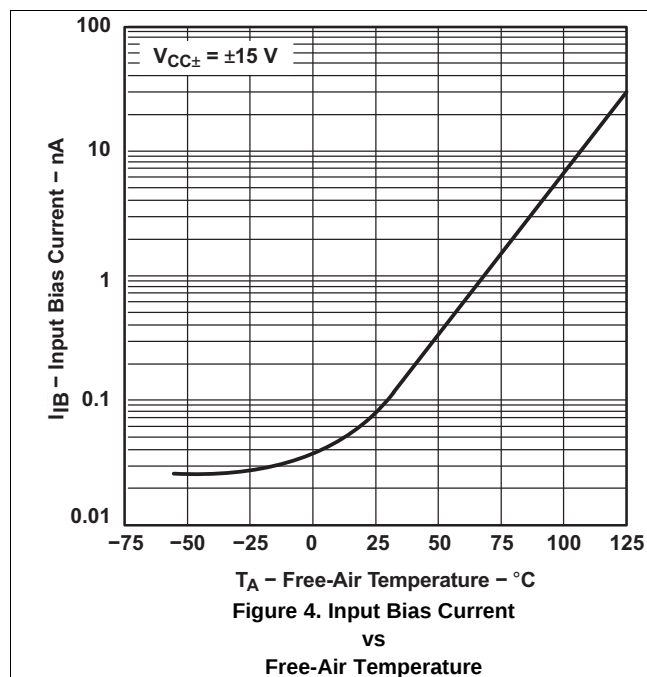
Figure 3. Input Offset-Voltage Null Circuit

8 Typical Characteristics

Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

Table of Graphs

			Figure
I_{IB}	Input bias current	versus Free-air temperature	Figure 4
V_{OM}	Maximum peak output voltage	versus Frequency versus Free-air temperature versus Load resistance versus Supply voltage	Figure 5, Figure 6, Figure 7 Figure 8 Figure 9 Figure 10
A_{VD}	Large signal differential voltage amplification	versus Free-air temperature versus Load resistance	Figure 11 Figure 12
	Phase shift	versus Frequency	Figure 12
	Normalized unity-gain bandwidth	versus Free-air temperature	Figure 13
	Normalized phase shift	versus Free-air temperature	Figure 13
CMRR	Common-mode rejection ratio	versus Free-air temperature	Figure 14
I_{CC}	Supply current	versus Free-air temperature versus Supply voltage	Figure 15 Figure 16
P_D	Total power dissipation	versus Free-air temperature	Figure 17
	Normalized slew rate	versus Free-air temperature	Figure 18
V_n	Equivalent input noise voltage	versus Frequency	Figure 19
THD	Total harmonic distortion	versus Frequency	Figure 20
	Large-signal pulse response	versus Time	Figure 21
V_O	Output voltage	versus Elapsed time	Figure 22



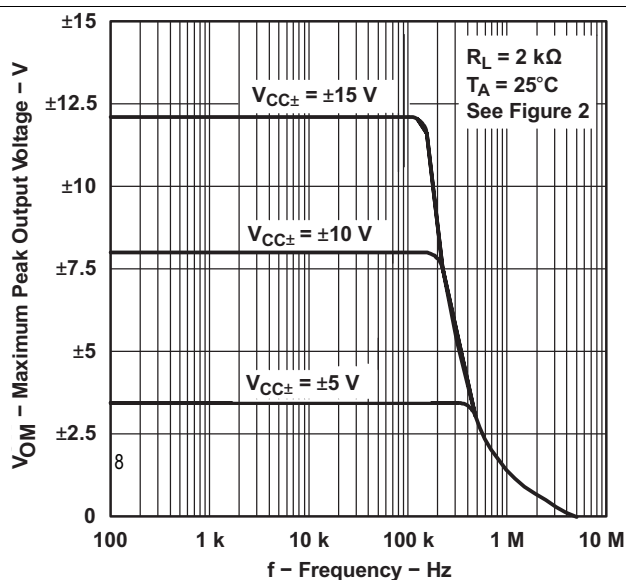


Figure 6. Maximum Peak Output Voltage
vs
Frequency

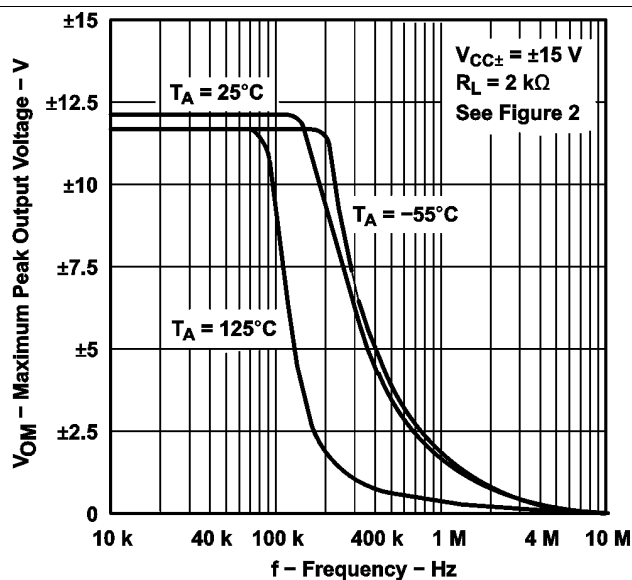


Figure 7. Maximum Peak Output Voltage
vs
Frequency

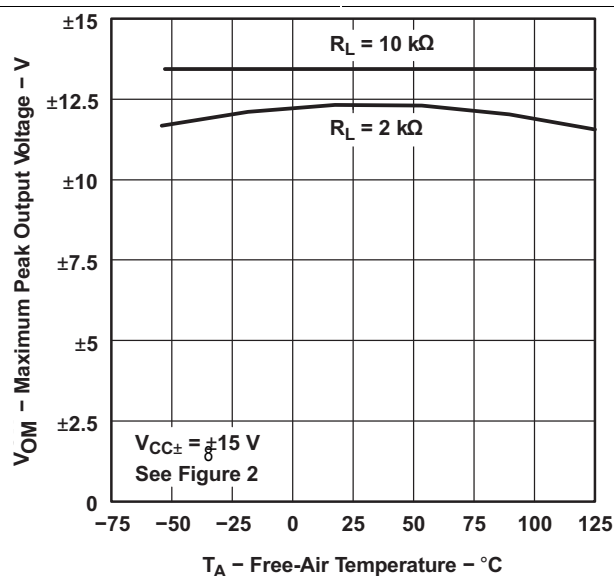


Figure 8. Maximum Peak Output Voltage
vs
Free-Air Temperature

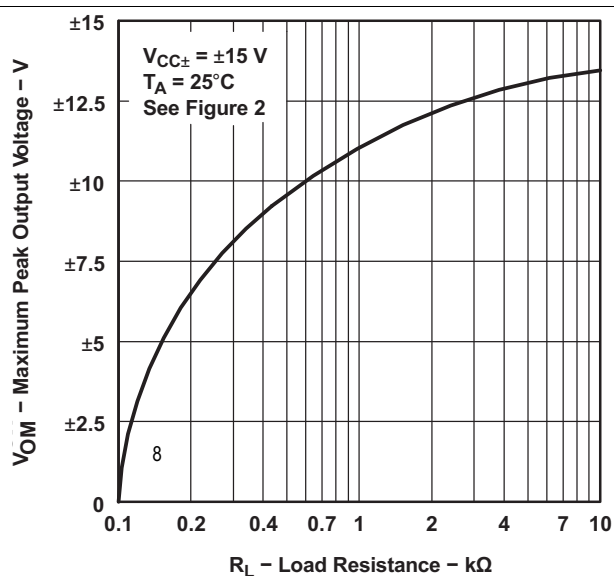


Figure 9. Maximum Peak Output Voltage
vs
Load Resistance

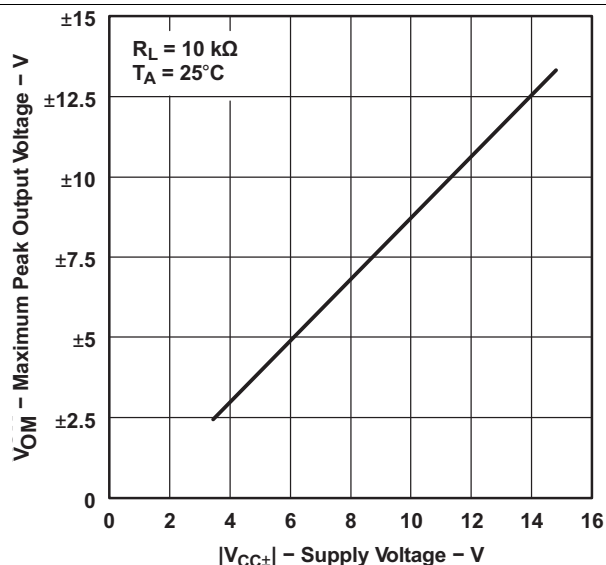


Figure 10. Maximum Peak Output Voltage
vs
Supply Voltage

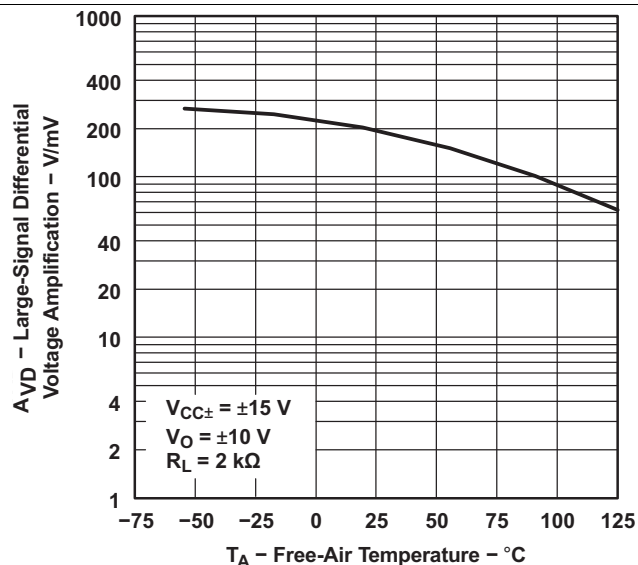


Figure 11. Large-Signal Differential Voltage Amplification
vs
Free-Air Temperature

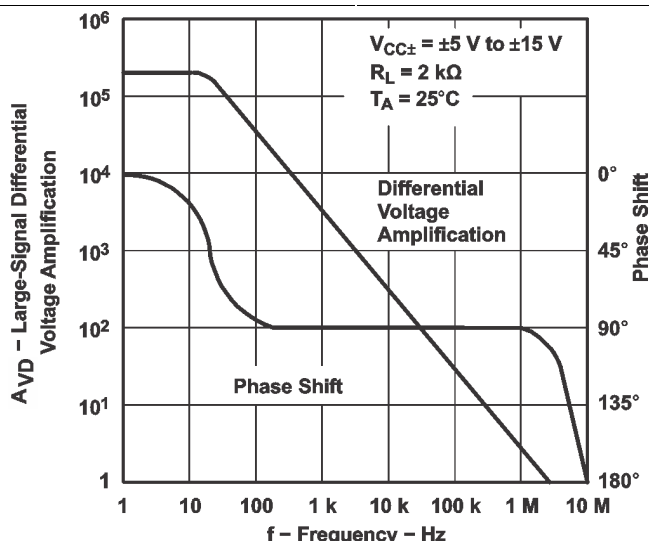


Figure 12. Large-Signal Differential Voltage Amplification
and Phase Shift
vs
Frequency

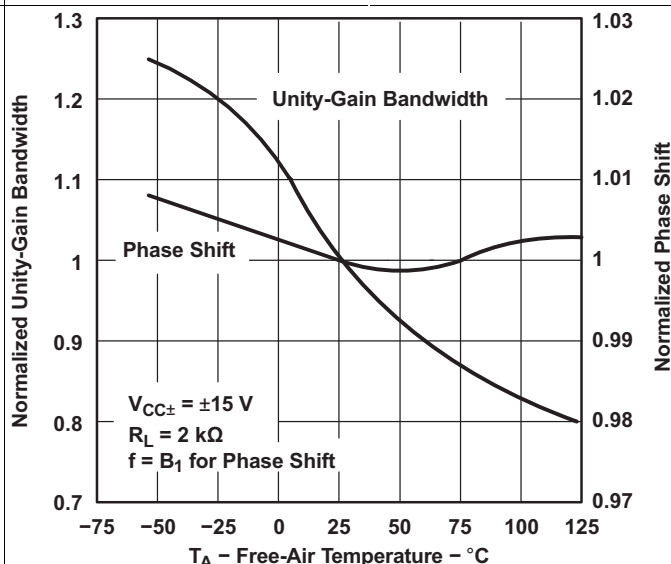
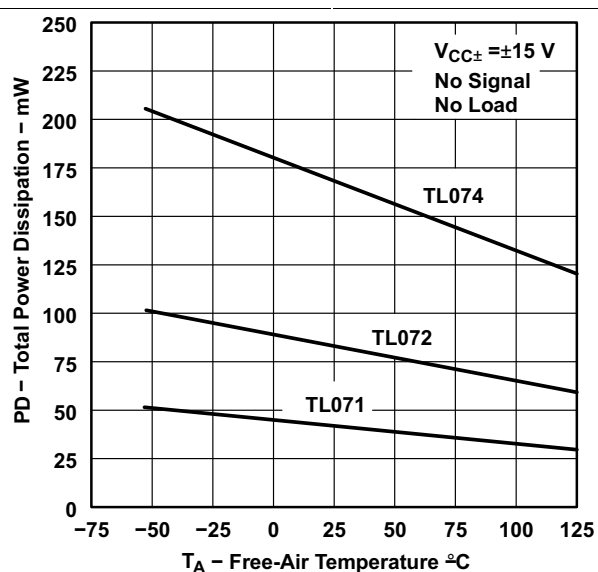
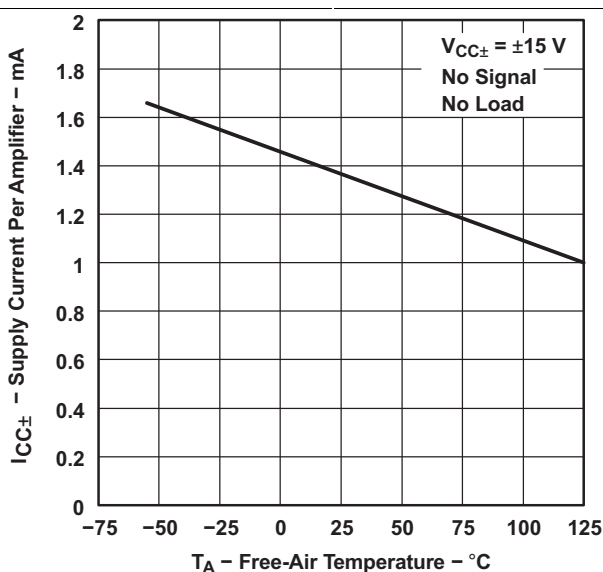
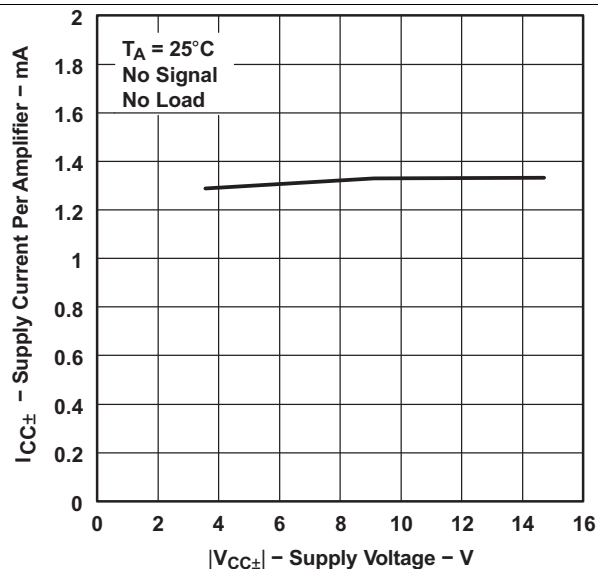
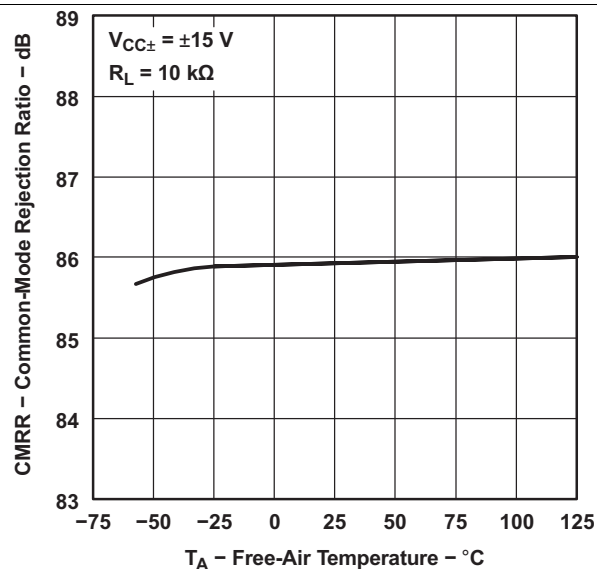


Figure 13. Normalized Unity-Gain Bandwidth and Phase
Shift
vs
Free-Air Temperature



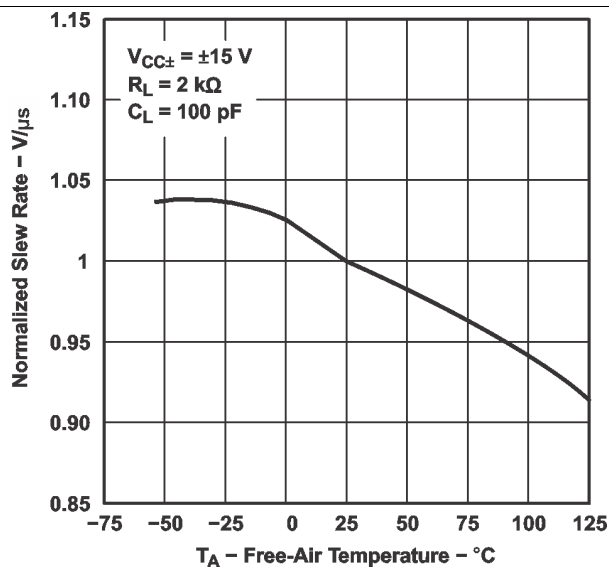


Figure 18. Normalized Slew Rate
vs
Free-Air Temperature

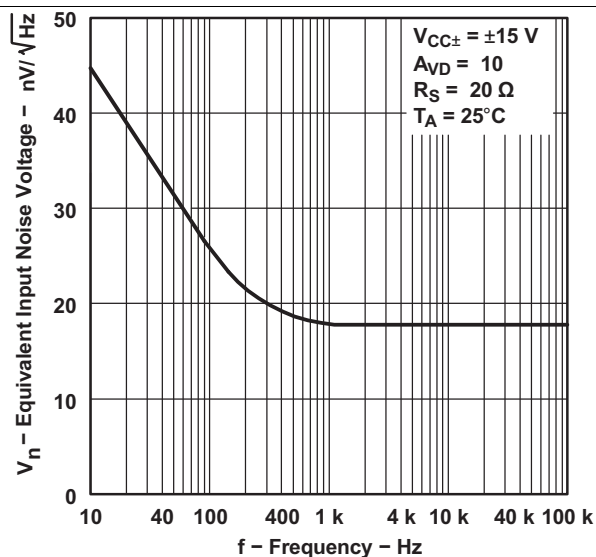


Figure 19. Equivalent Input Noise Voltage
vs
Frequency

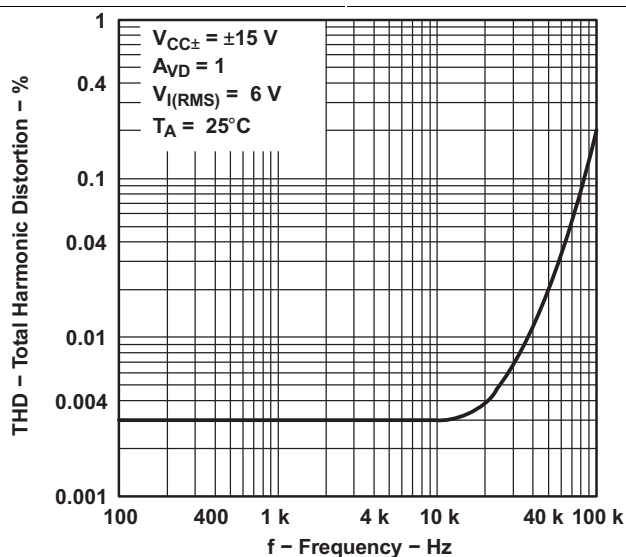


Figure 20. Total Harmonic Distortion
vs
Frequency

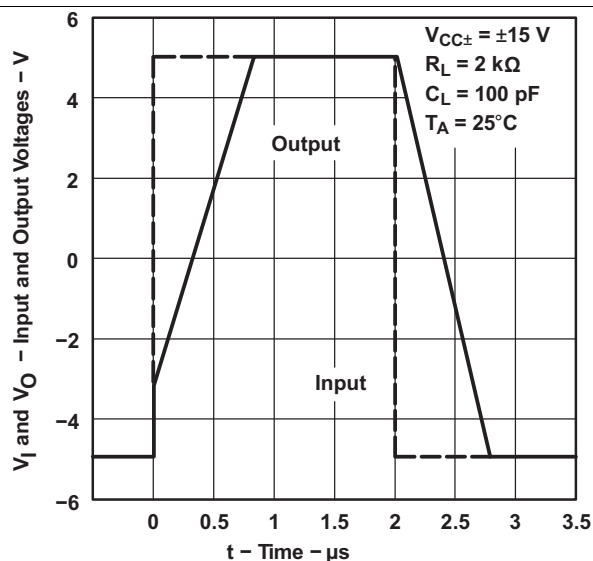


Figure 21. Voltage-Follower Large-Signal Pulse Response

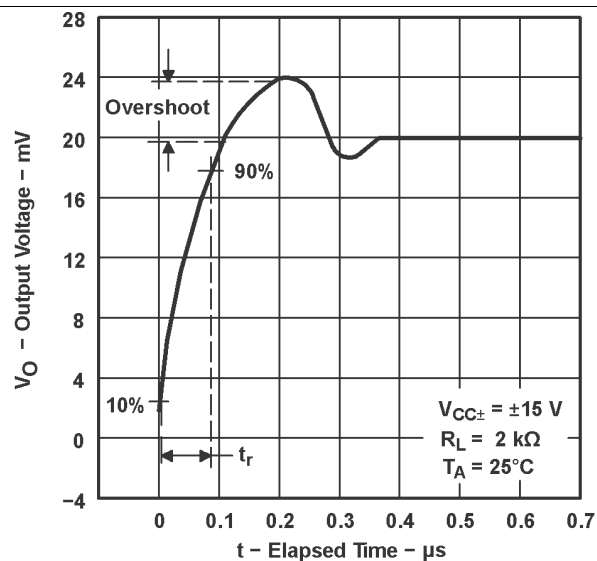


Figure 22. Output Voltage
vs
Elapsed Time

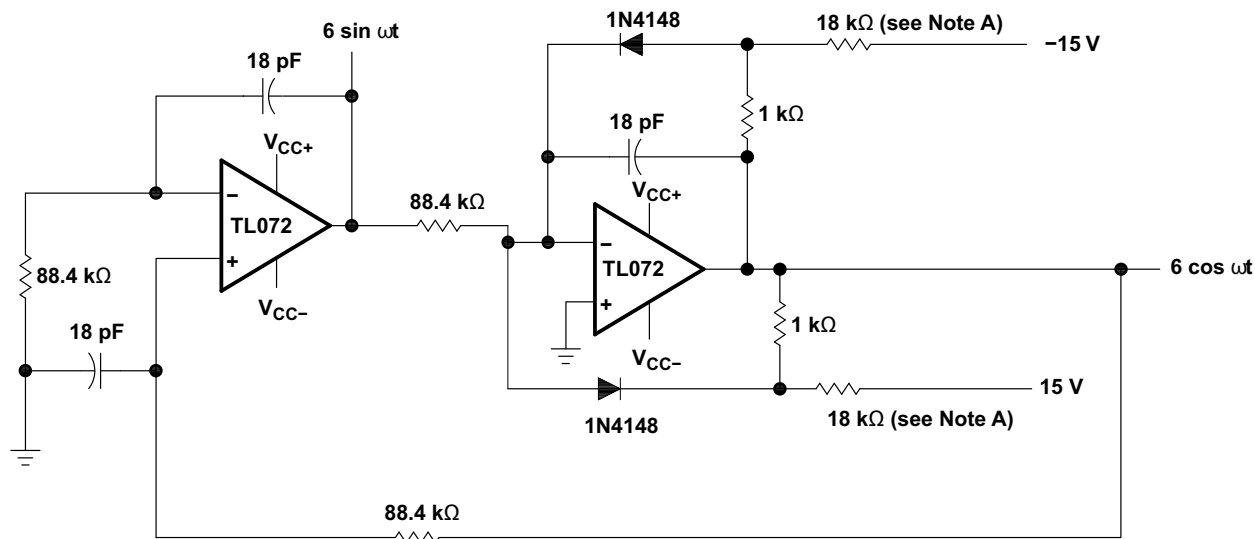


Figure 26. 100-kHz Quadrature Oscillator

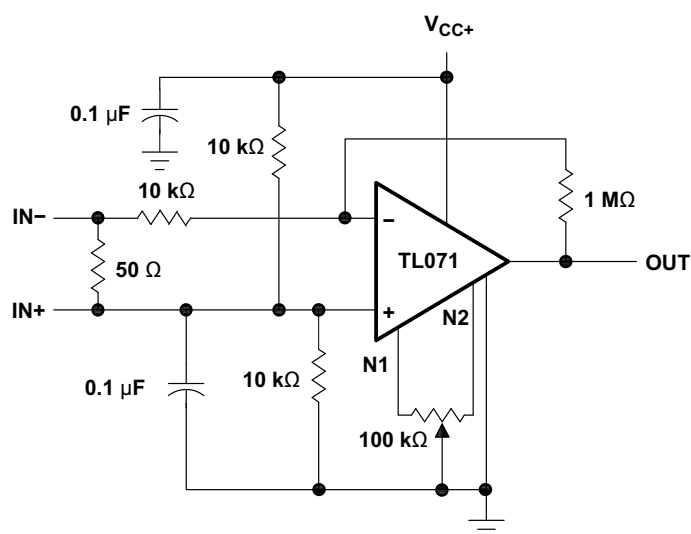


Figure 27. AC Amplifier

10 Device and Documentation Support

10.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
TL071	Click here	Click here	Click here	Click here	Click here
TL071A	Click here	Click here	Click here	Click here	Click here
TL071B	Click here	Click here	Click here	Click here	Click here
TL072	Click here	Click here	Click here	Click here	Click here
TL072A	Click here	Click here	Click here	Click here	Click here
TL072B	Click here	Click here	Click here	Click here	Click here
TL074	Click here	Click here	Click here	Click here	Click here
TL074A	Click here	Click here	Click here	Click here	Click here
TL074B	Click here	Click here	Click here	Click here	Click here

10.2 Trademarks

All trademarks are the property of their respective owners.

10.3 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

10.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms and definitions.

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
8102304HA	OBSOLETE			10		TBD	Call TI	Call TI	-55 to 125		
81023052A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	81023052A TL072MFKB	Samples
8102305HA	ACTIVE	CFP	U	10	1	TBD	A42	N / A for Pkg Type	-55 to 125	8102305HA TL072M	Samples
8102305PA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	8102305PA TL072M	Samples
81023062A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	81023062A TL074MFKB	Samples
8102306CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8102306CA TL074MJB	Samples
8102306DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8102306DA TL074MWB	Samples
JM38510/11905BPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510 /11905BPA	Samples
JM38510/11906BCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
M38510/11905BPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510 /11905BPA	Samples
TL071-W	ACTIVE	WAFERSALE	YS	0		TBD	Call TI	Call TI			Samples
TL071ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	071AC	Samples
TL071ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	071AC	Samples
TL071ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	071AC	Samples
TL071ACP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL071ACP	Samples
TL071ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL071ACP	Samples
TL071BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	071BC	Samples
TL071BCDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	071BC	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL071BCDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	071BC	Samples
TL071BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	071BC	Samples
TL071BCP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL071BCP	Samples
TL071BCPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL071BCP	Samples
TL071CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL071C	Samples
TL071CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL071C	Samples
TL071CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL071C	Samples
TL071CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL071C	Samples
TL071CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL071CP	Samples
TL071CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL071CP	Samples
TL071CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T071	Samples
TL071CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T071	Samples
TL071CPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	0 to 70		
TL071ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL071I	Samples
TL071IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL071I	Samples
TL071IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL071I	Samples
TL071IJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	-40 to 85		
TL071IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL071IP	Samples
TL071IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL071IP	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL071MFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
TL071MJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	-55 to 125		
TL071MJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	-55 to 125		
TL072ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	072AC	Samples
TL072ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	072AC	Samples
TL072ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	072AC	Samples
TL072ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	072AC	Samples
TL072ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	072AC	Samples
TL072ACJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	0 to 70		
TL072ACP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL072ACP	Samples
TL072ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL072ACP	Samples
TL072ACPSR	OBSOLETE	SO	PS	8		TBD	Call TI	Call TI	0 to 70	T072A	
TL072ACPSRE4	OBSOLETE	SO	PS	8		TBD	Call TI	Call TI	0 to 70		
TL072ACPSRG4	OBSOLETE	SO	PS	8		TBD	Call TI	Call TI	0 to 70		
TL072BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	072BC	Samples
TL072BCDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	072BC	Samples
TL072BCDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	072BC	Samples
TL072BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	072BC	Samples
TL072BCDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	072BC	Samples
TL072BCDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	072BC	Samples
TL072BCP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL072BCP	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL072BCPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL072BCP	Samples
TL072CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL072C	Samples
TL072CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL072C	Samples
TL072CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL072C	Samples
TL072CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL072C	Samples
TL072CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL072C	Samples
TL072CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL072C	Samples
TL072CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL072CP	Samples
TL072CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL072CP	Samples
TL072CPSLE	OBSOLETE	SO	PS	8		TBD	Call TI	Call TI	0 to 70		
TL072CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T072	Samples
TL072CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T072	Samples
TL072CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T072	Samples
TL072CPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T072	Samples
TL072CPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T072	Samples
TL072CPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T072	Samples
TL072ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL072I	Samples
TL072IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL072I	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL072IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL072I	Samples
TL072IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL072I	Samples
TL072IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL072I	Samples
TL072IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL072I	Samples
TL072IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL072IP	Samples
TL072IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL072IP	Samples
TL072MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	81023052A TL072MFKB	Samples
TL072MJG	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	TL072MJG	Samples
TL072MJGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	8102305PA TL072M	Samples
TL072MUB	ACTIVE	CFP	U	10	1	TBD	A42	N / A for Pkg Type	-55 to 125	8102305HA TL072M	Samples
TL074ACD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074AC	Samples
TL074ACDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074AC	Samples
TL074ACDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074AC	Samples
TL074ACDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074AC	Samples
TL074ACDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074AC	Samples
TL074ACDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074AC	Samples
TL074ACJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
TL074ACN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL074ACN	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL074ACNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL074ACN	Samples
TL074ACNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074A	Samples
TL074BCD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074BC	Samples
TL074BCDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074BC	Samples
TL074BCDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074BC	Samples
TL074BCDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074BC	Samples
TL074BCDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074BC	Samples
TL074BCDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074BC	Samples
TL074BCN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL074BCN	Samples
TL074BCNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL074BCN	Samples
TL074CD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074C	Samples
TL074CDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074C	Samples
TL074CDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074C	Samples
TL074CDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	0 to 70	TL074C	Samples
TL074CDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074C	Samples
TL074CDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074C	Samples
TL074CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL074CN	Samples
TL074CNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL074CN	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL074CNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074	Samples
TL074CNSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL074	Samples
TL074CPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T074	Samples
TL074CPWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T074	Samples
TL074CPWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	0 to 70		
TL074CPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T074	Samples
TL074CPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T074	Samples
TL074CPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T074	Samples
TL074ID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL074I	Samples
TL074IDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL074I	Samples
TL074IDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL074I	Samples
TL074IDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL074I	Samples
TL074IDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL074I	Samples
TL074IDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL074I	Samples
TL074IJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-40 to 85		
TL074IN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL074IN	Samples
TL074INE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL074IN	Samples
TL074MFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	TL074MFK	Samples
TL074MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	81023062A TL074MFKB	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL074MJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	TL074MJ	Samples
TL074MJB	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8102306CA TL074MJB	Samples
TL074MWB	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8102306DA TL074MWB	Samples
TL081-W	ACTIVE	WAFERSALE	YS	0		TBD	Call TI	Call TI			Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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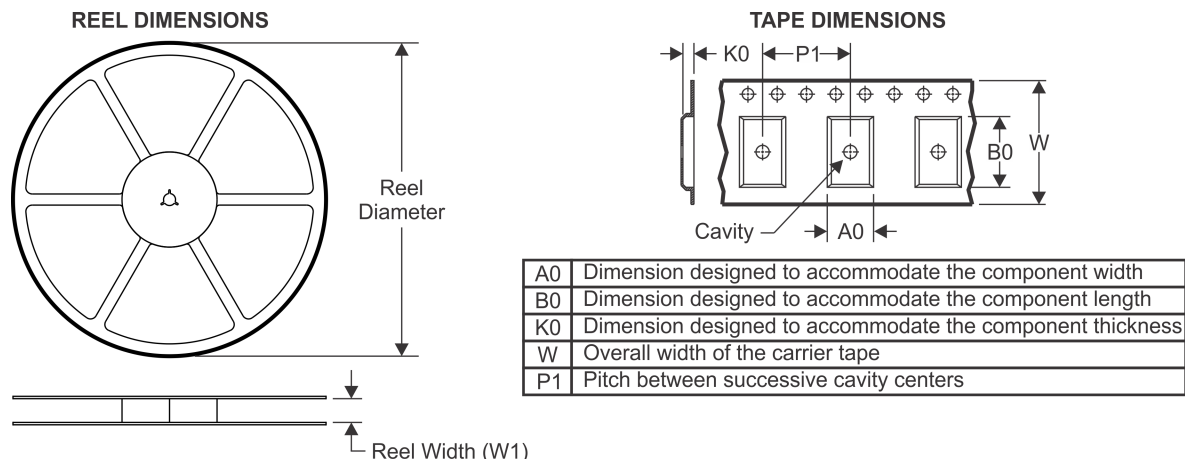
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OTHER QUALIFIED VERSIONS OF TL072, TL072M, TL074, TL074M :

- Catalog: [TL072](#), [TL074](#)
- Enhanced Product: [TL072-EP](#), [TL072-EP](#), [TL074-EP](#), [TL074-EP](#)
- Military: [TL072M](#), [TL074M](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

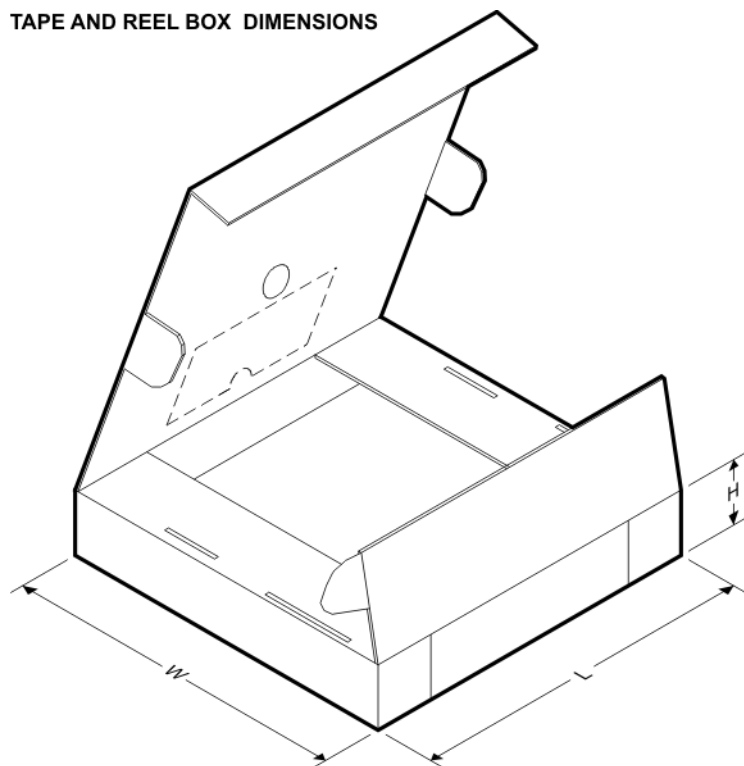
TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL071ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL071BCDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL071CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL071CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL071CPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
TL071IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL072ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL072BCDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL072CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL072CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL072CPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TL072IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL072IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL074ACDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL074ACNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
TL074BCDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL074CDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL074CDRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL074CPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TL074IDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



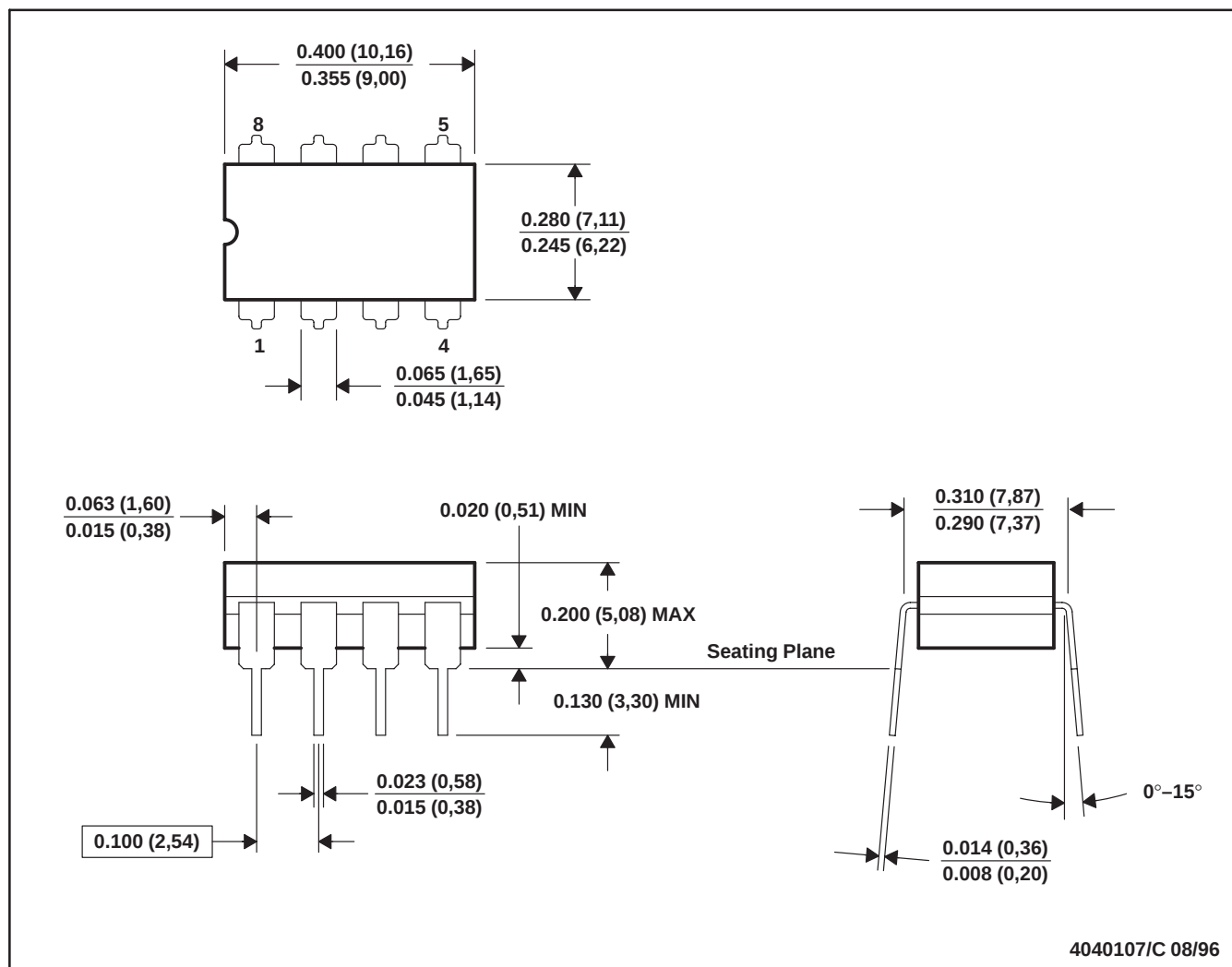
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL071ACDR	SOIC	D	8	2500	340.5	338.1	20.6
TL071BCDR	SOIC	D	8	2500	340.5	338.1	20.6
TL071CDR	SOIC	D	8	2500	340.5	338.1	20.6
TL071CDR	SOIC	D	8	2500	367.0	367.0	35.0
TL071CPSR	SO	PS	8	2000	367.0	367.0	38.0
TL071IDR	SOIC	D	8	2500	340.5	338.1	20.6
TL072ACDR	SOIC	D	8	2500	340.5	338.1	20.6
TL072BCDR	SOIC	D	8	2500	340.5	338.1	20.6
TL072CDR	SOIC	D	8	2500	340.5	338.1	20.6
TL072CDR	SOIC	D	8	2500	367.0	367.0	35.0
TL072CPWR	TSSOP	PW	8	2000	367.0	367.0	35.0
TL072IDR	SOIC	D	8	2500	367.0	367.0	35.0
TL072IDR	SOIC	D	8	2500	340.5	338.1	20.6
TL074ACDR	SOIC	D	14	2500	333.2	345.9	28.6
TL074ACNSR	SO	NS	14	2000	367.0	367.0	38.0

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL074BCDR	SOIC	D	14	2500	333.2	345.9	28.6
TL074CDR	SOIC	D	14	2500	333.2	345.9	28.6
TL074CDRG4	SOIC	D	14	2500	333.2	345.9	28.6
TL074CPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
TL074IDR	SOIC	D	14	2500	333.2	345.9	28.6

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE

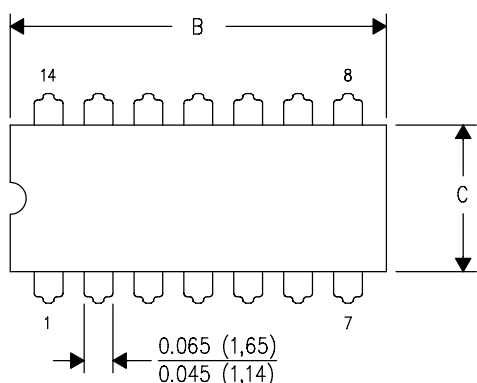


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification.
 E. Falls within MIL STD 1835 GDIP1-T8

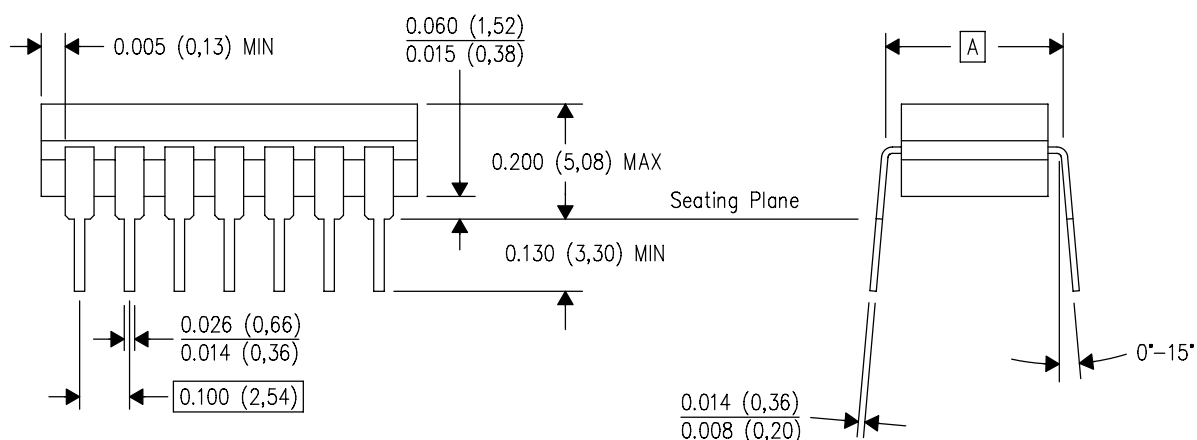
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

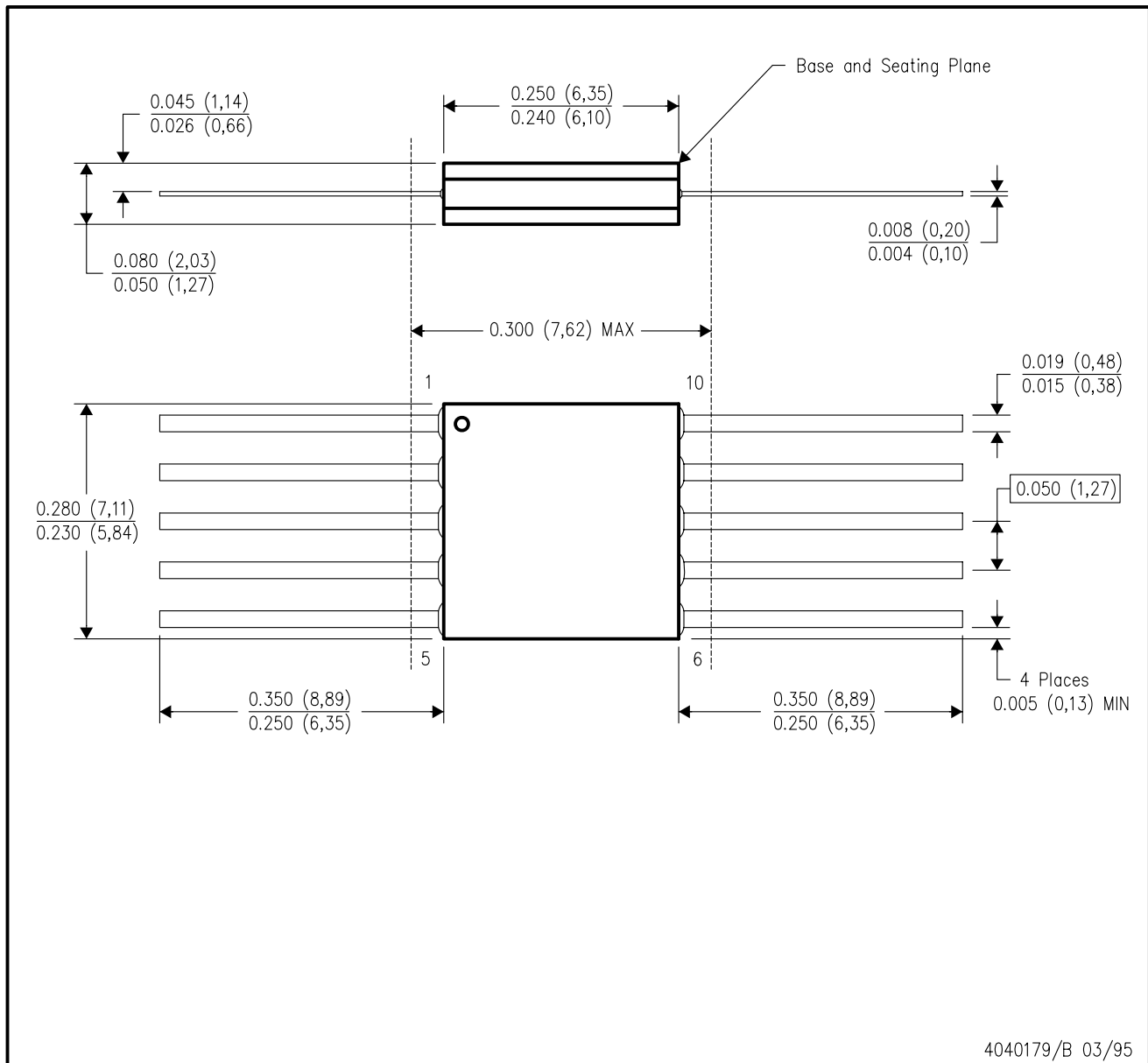


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

U (S-GDFP-F10)

CERAMIC DUAL FLATPACK



4040179/B 03/95

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



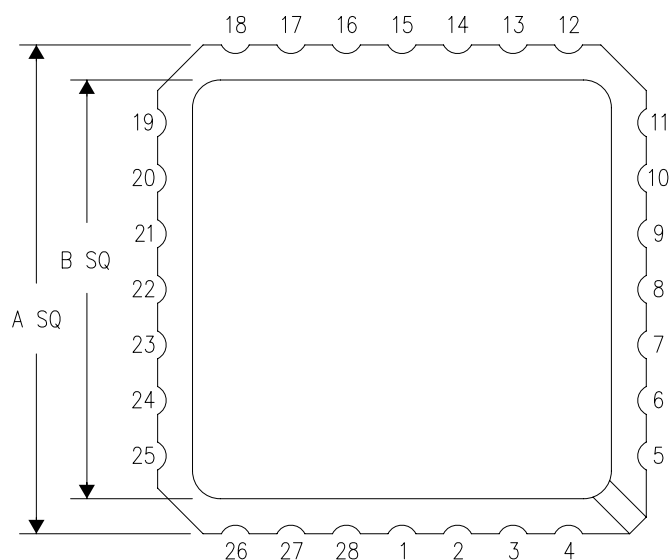
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within MIL STD 1835 GDFP1-F14

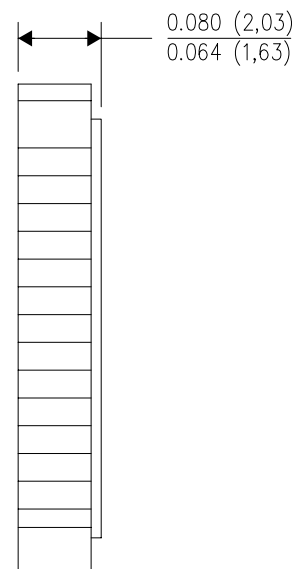
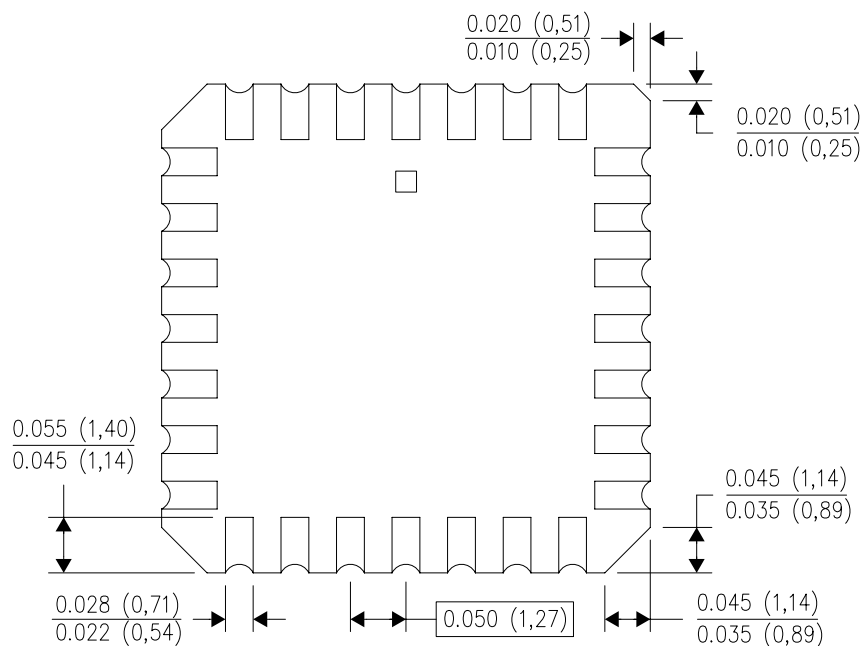
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



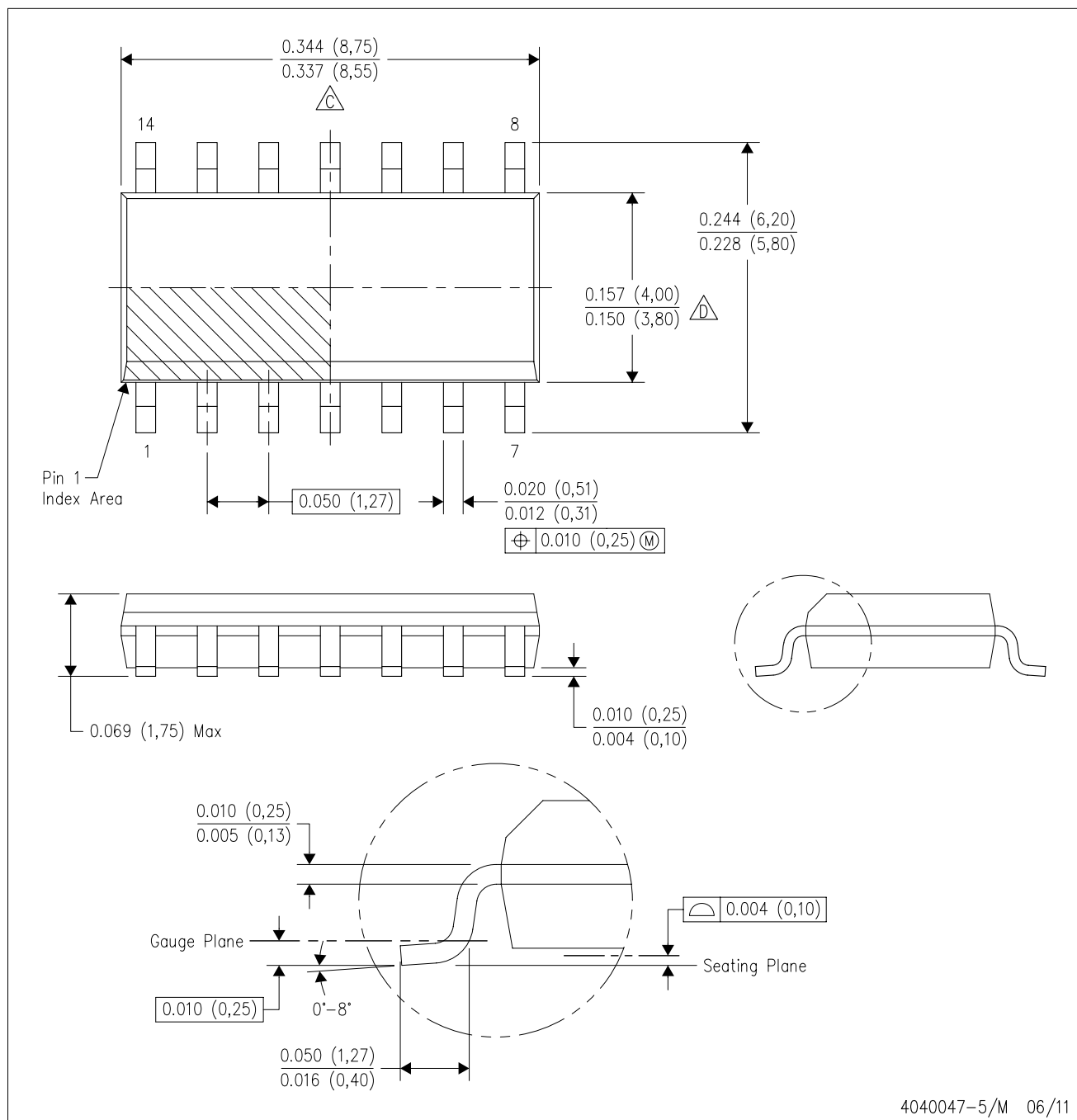
4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

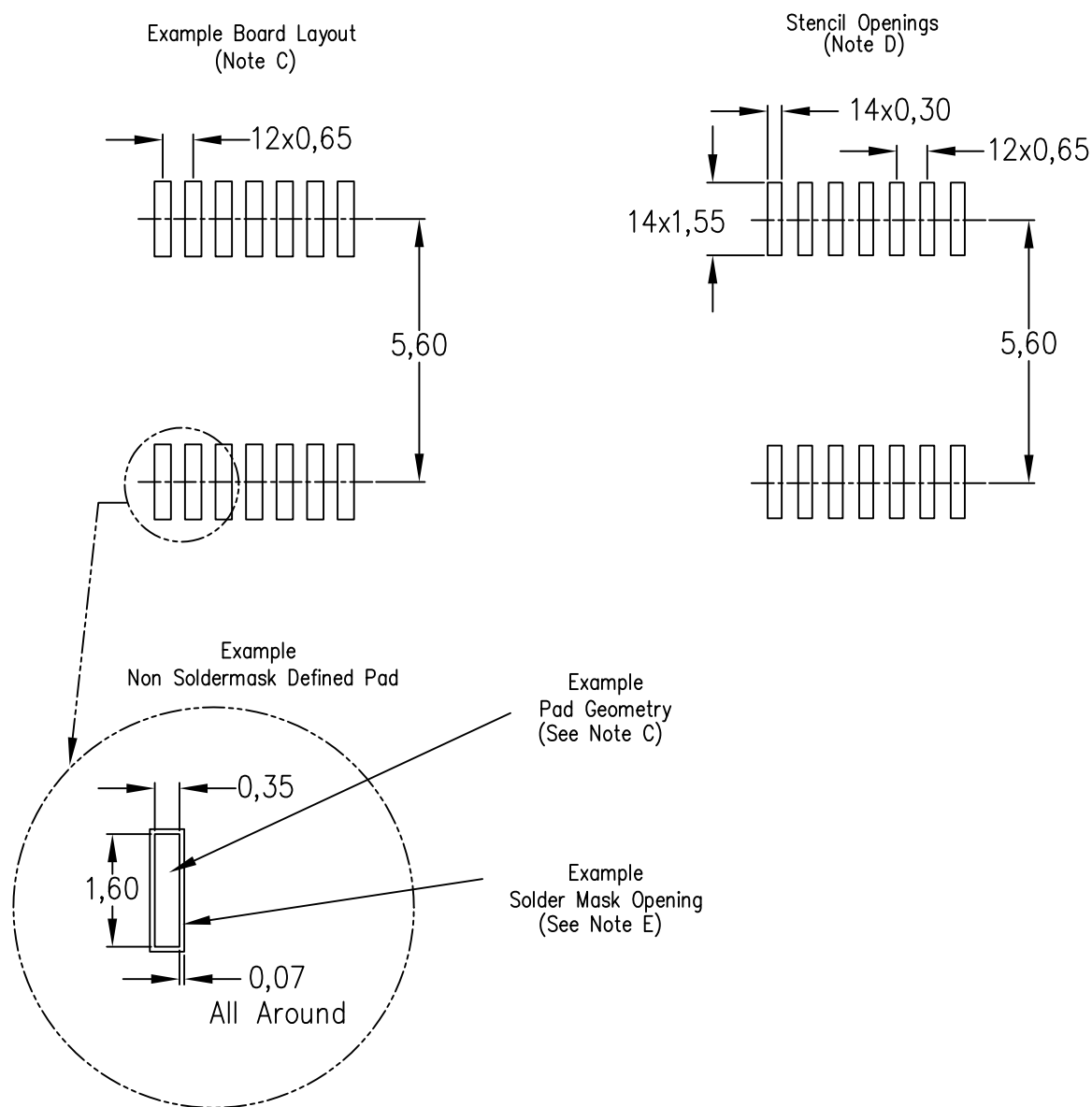
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

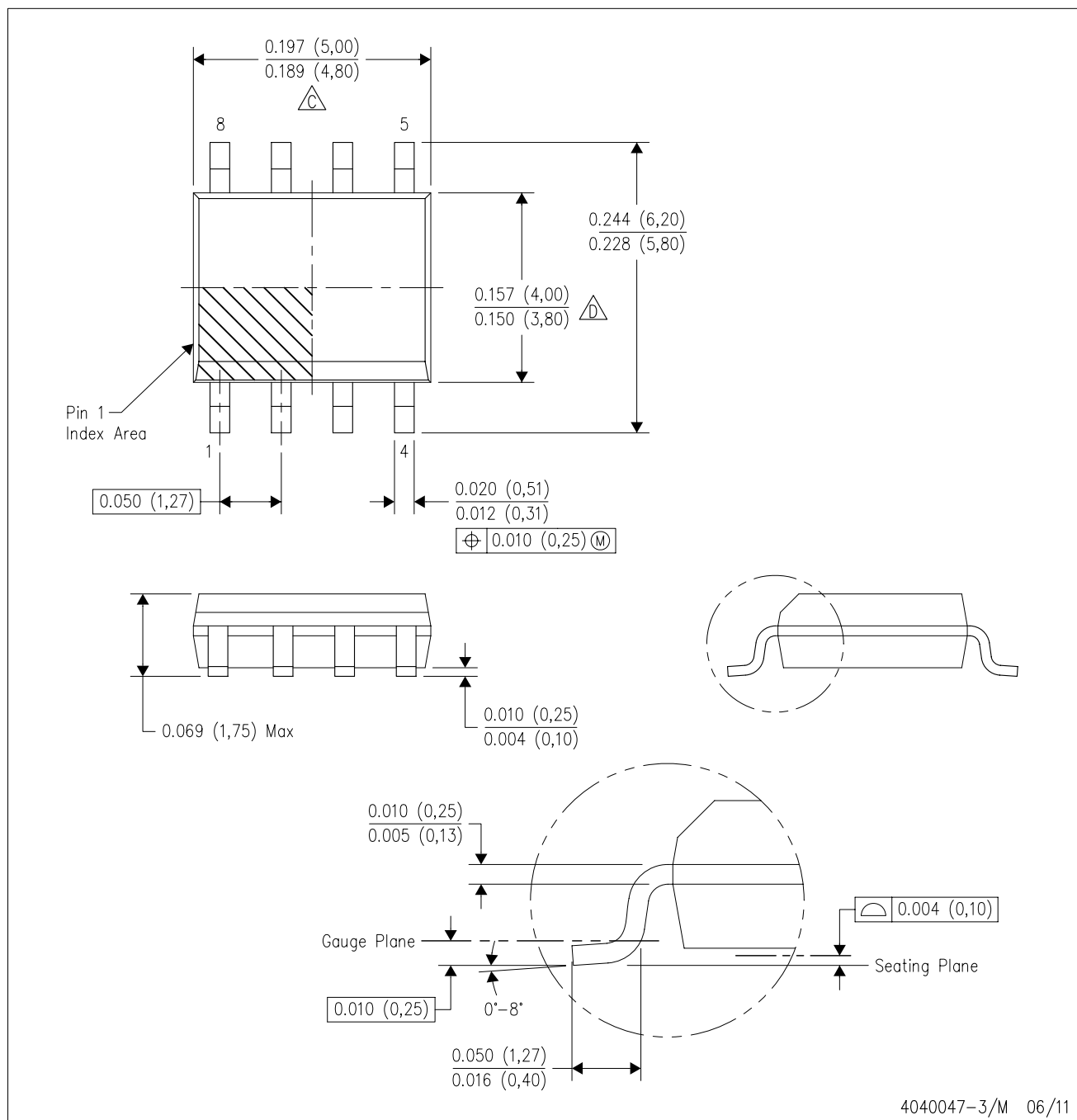


4211284-2/F 12/12

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE

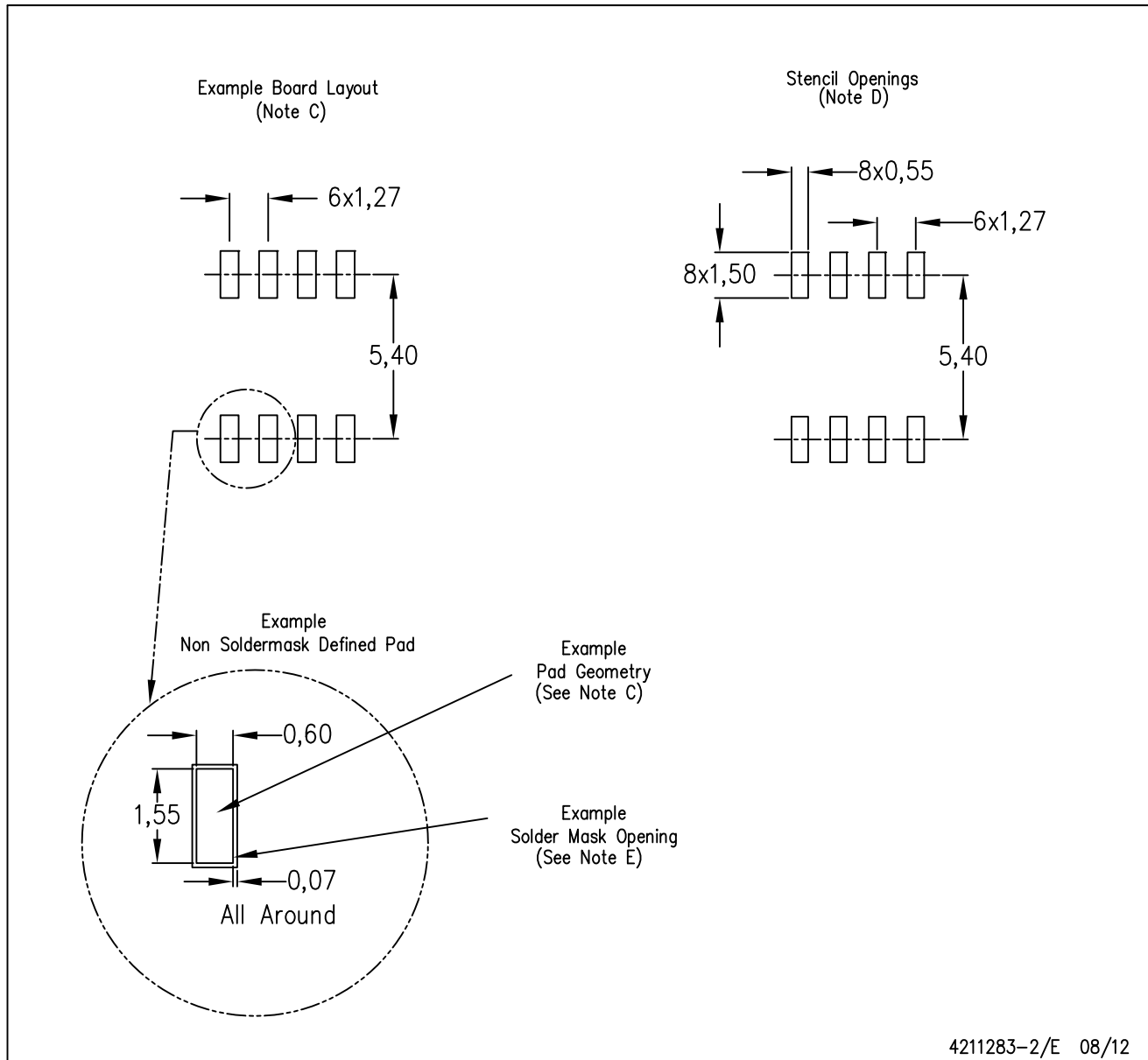


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE

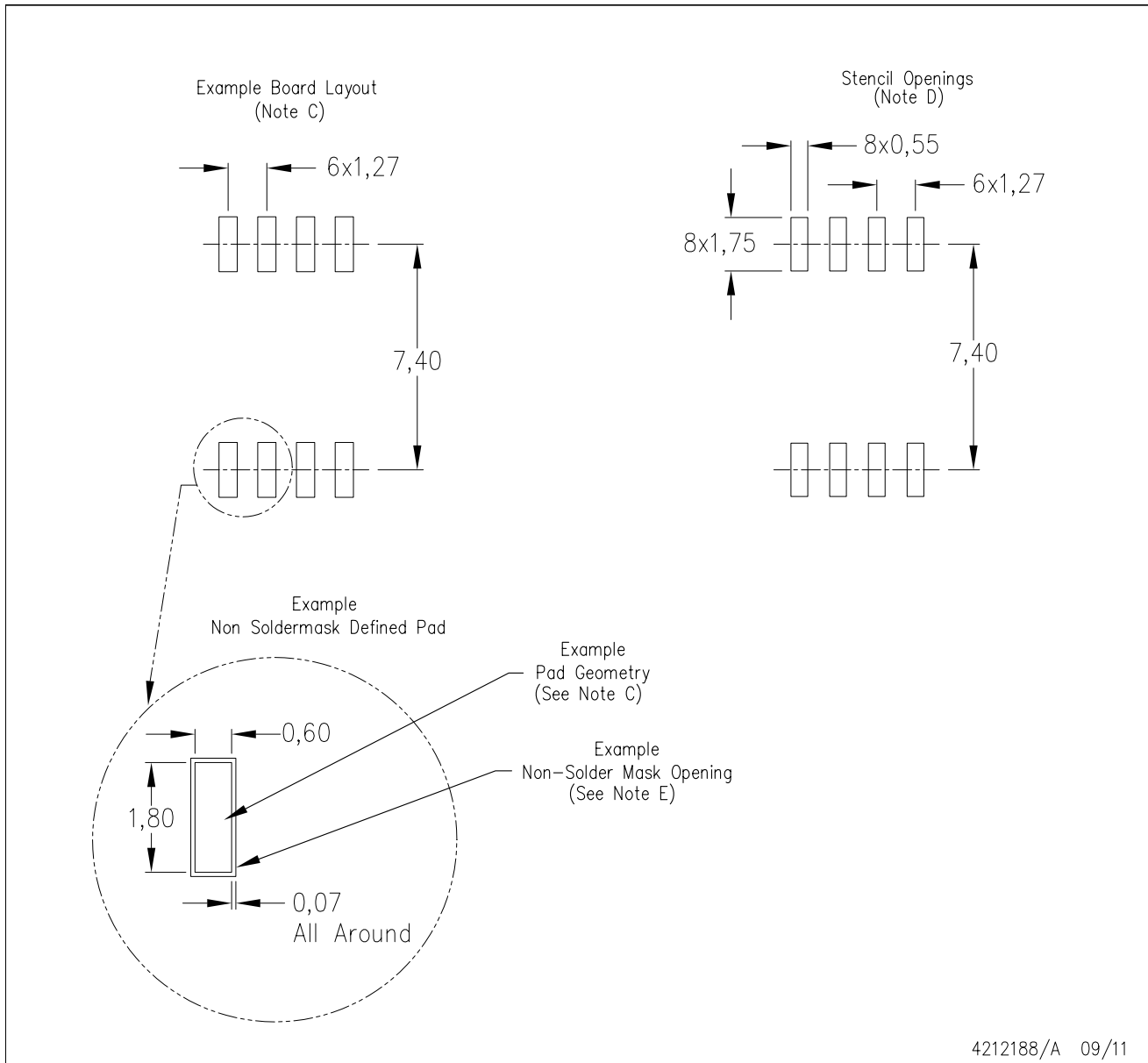


4040063/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PS (R-PDSO-G8)

PLASTIC SMALL OUTLINE



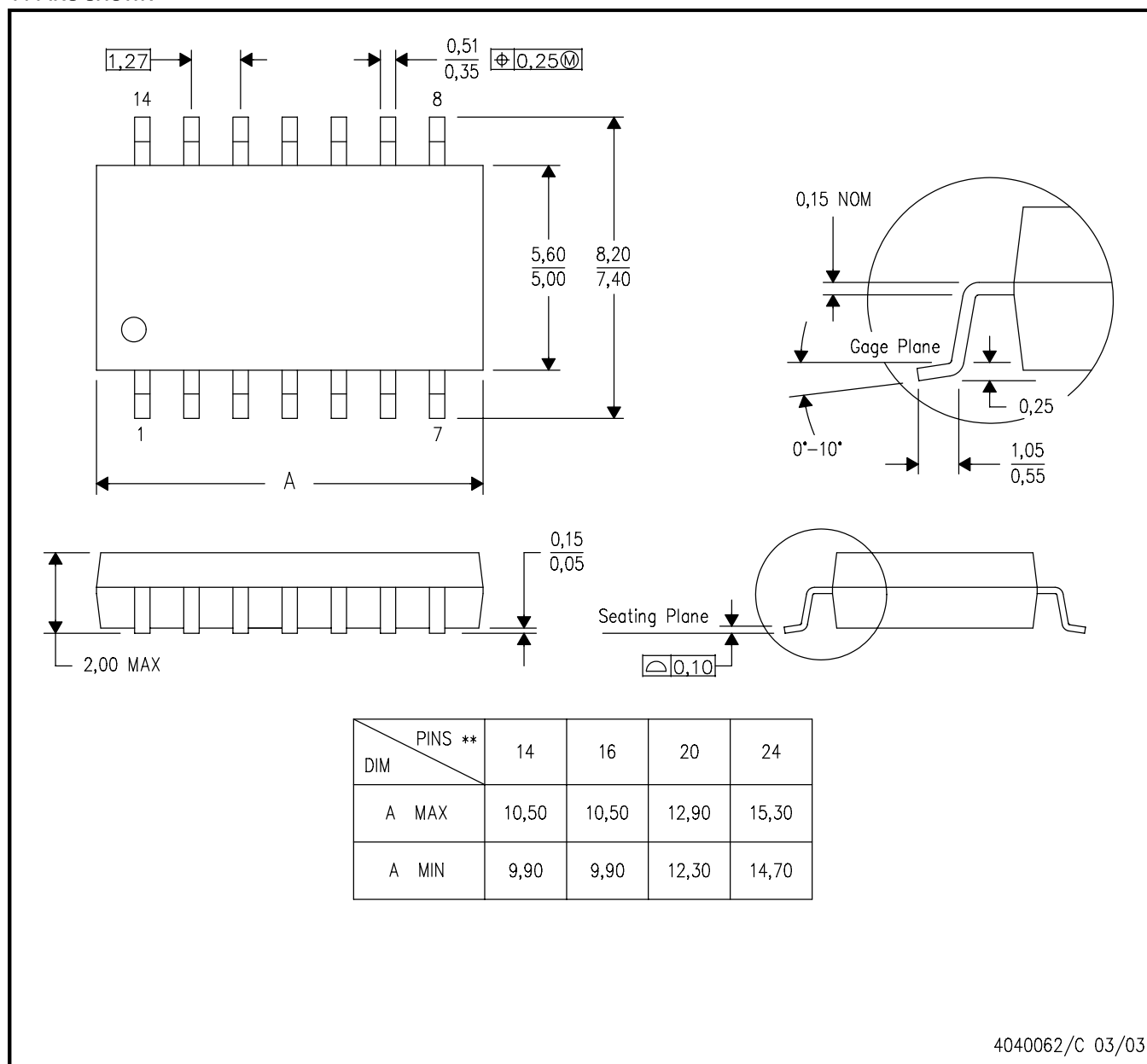
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

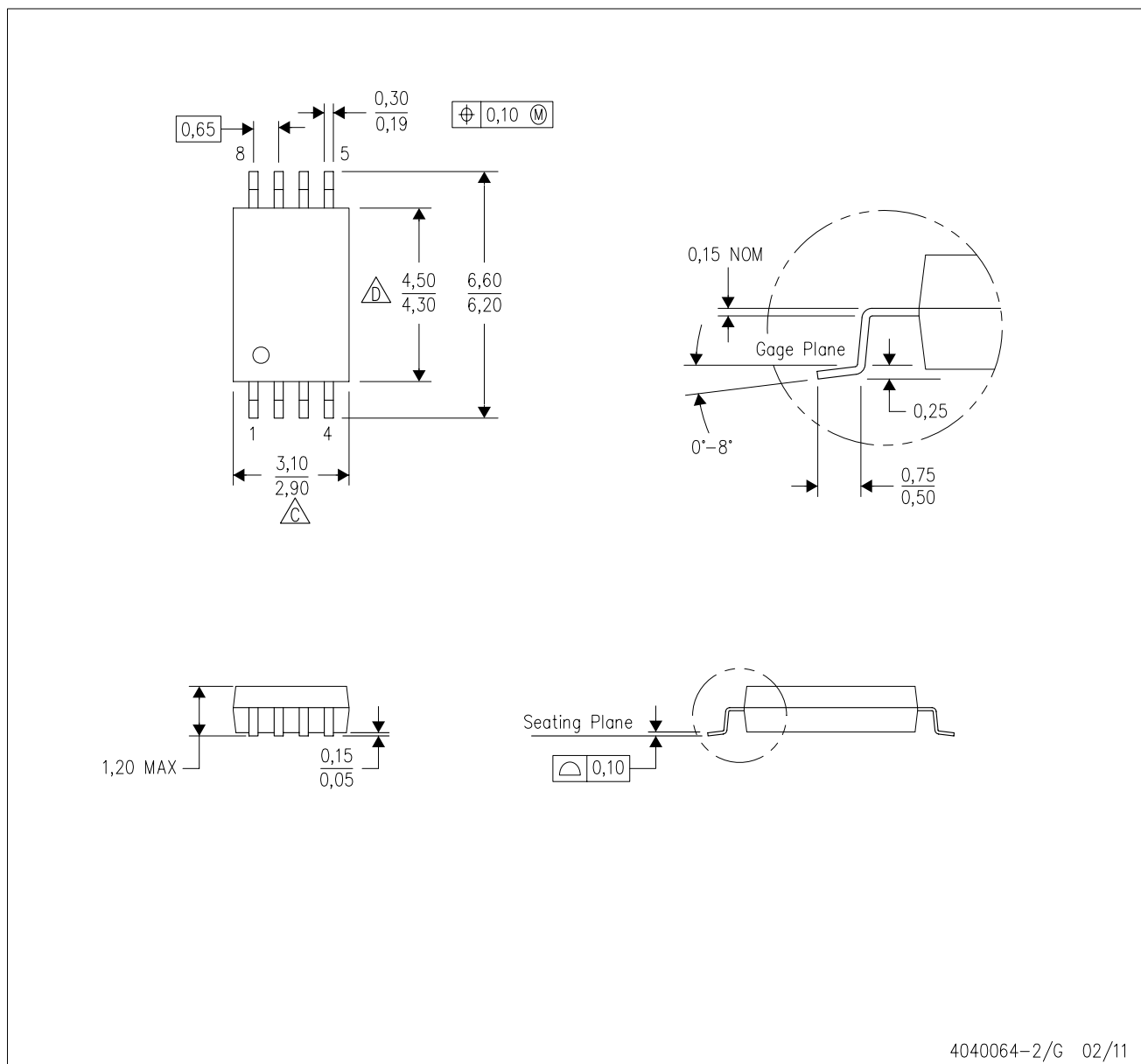
14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

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